

Claims

1. A circuit arrangement having
5 a component (2) to be cooled,

comprising

an electrical component in the form of a heat
10 sink, which is an active part of the circuit
arrangement, in particular an inductive component
(4) having a core, and

a heat transfer device (3), which is arranged
15 between the component (2) to be cooled and the
electrical component in the form of a heat sink
such that it is in direct contact with the two for
the purpose of removing heat from the component
(2) to be cooled.
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2. The circuit arrangement as claimed in claim 1, in
which the heat transfer device (3) comprises a
resilient mat.
- 25 3. The circuit arrangement as claimed in claim 2, in
which the mat is produced from a foamed mass.
4. The circuit arrangement as claimed in claim 1, in
which the inductive component (4) is a
30 transformer.
5. The circuit arrangement as claimed in claim 1, in
which the component (2) to be cooled is an
integrated circuit.

6. The circuit arrangement as claimed in claim 4, in which the component (2) to be cooled is an integrated circuit.
- 5 7. The circuit arrangement as claimed in claim 1, which has two or more components (2) to be cooled, the heat transfer device (3) being arranged jointly thereover.
- 10 8. A method for cooling an electronic component (2) of an electrical circuit by

providing the component (2) to be cooled of the electrical circuit,
15 providing an electrical component, actively participating in the electrical circuit, in the form of a heat sink, in particular an inductive component (4), which has a core, and
20 inserting a heat transfer device (3) between the component (2) to be cooled and the component acting as the heat sink such that it is in direct contact with the two for the purpose of removing
25 heat from the component (2) to be cooled.
9. The method as claimed in claim 8, in which the heat transfer device (3) comprises a resilient mat.
- 30 10. The method as claimed in claim 9, in which the mat is produced from a foamed mass.
11. The method as claimed in claim 8, in which the
35 inductive component (4) is a transformer.

12. The method as claimed in claim 8, in which the component (2) to be cooled is an integrated circuit.
- 5 13. The method as claimed in claim 11, in which the component (2) to be cooled is an integrated circuit.
- 10 14. The method as claimed in claim 8, in which two or more components (2) to be cooled are provided, which are cooled jointly with the aid of the heat transfer device (3) on the component acting as the heat sink.